

AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended): A resin plating method with an added partial heat-treating process for plating a resin molding composed of mixture of two or more different resins [,] in which a rubber component is dispersed, comprising:

partially heat-treating only the parting line portion of said resin molding at a high temperature within a range from the heat deformation temperature of the resin to the resin molding temperature, and

metal plating the resin molding undergoing high-temperature partial heat treating
~~resin plating is performed after a specific portion of the resin molding which portion is apt to undergo peeling of a thin surface resin film of the resin molding is heat-treated at a high temperature~~
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temperature.

Claims 2 and 3: Canceled

Claim 4 (Currently Amended): ~~A~~ The resin plating method with an added partial heat-treating process according to claim 1, wherein the resin molding is heat-treated at a high temperature ~~so that~~ for the rubber particles in the resin surface of the resin molding to retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claims 5-16: Canceled.

Claim 17 (New): The resin plating method with an added partial heat-treatment process according to claim 1, wherein a resin molding is made of ABS resin, PC/ABS resin, PC/PET resin, PC/PBT resin, POM resin, PPE resin, LCP resin, PPS resin, PS resin or SPS resin.

Claim 18 (New): The resin plating method with an added partial heat-treatment process according to claim 1, wherein the resin molding is made of PC/ABS resin and the high-

temperature partial heat treatment is performed within the heating temperature range to achieve surface temperature of the resin molding being between 100°C and 200°C.

Claim 19 (New): The resin plating method with an added partial heat-treatment process according to claim 1, wherein a suitable heat-treating time is in the range from 10 seconds to 40 seconds.

Claim 20 (New): A resin plating method with an added partial heat-treating process for plating a resin molding composed of mixture of two or more different resins in which a rubber component is dispersed, consisting of:

partially heat-treating only the parting line portion of said resin molding at a high temperature within a range from the heat deformation temperature of the resin to the resin molding temperature, and

metal plating the resin molding undergoing high-temperature partial heat treating,
wherein the resin molding is heat-treated at a high temperature ~~so that~~ for the rubber particles in the resin surface of the resin molding to retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions, and

wherein the resin molding is made of PC/ABS resin and the high-temperature partial heat treatment is performed within the heating temperature range to achieve surface temperature of the resin molding being between 100°C and 200°C.